

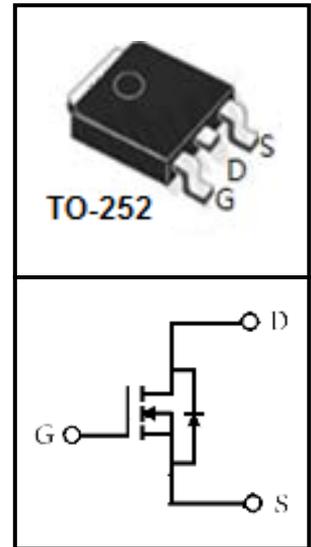
20V N-Channel Trench MOSFET

FEATURES

- Super Low Gate Charge
- 100% EAS Guaranteed
- RoHS compliant
- Green Device Available
- Excellent CdV/dt effect decline
- Advanced high cell density Trench technology

APPLICATIONS

- Load Switching
- Hard switched and high frequency circuits
- Uninterruptible power supply



Device Marking and Package Information

Device	Package	Marking
CTD02N4P8	TO-252	CTD02N4P8

Absolute Maximum Ratings at $T_j = 25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Value	Unit
Drain-Source Voltage ($V_{GS} = 0\text{V}$)	V_{DSS}	20	V
Continuous Drain Current $T_C = 25^\circ\text{C}$ (note1)	I_D	80	A
Continuous Drain Current $T_C = 100^\circ\text{C}$ (note1)		57	A
Pulsed Drain Current (note2)	I_{DM}	320	A
Gate Source Voltage	V_{GSS}	± 12	V
Single Pulse Avalanche Energy (note3)	E_{AS}	6.5	mJ
Power Dissipation $T_C = 25^\circ\text{C}$ (note4)	P_D	87	W
Operating Junction and Storage Temperature Range	T_J, T_{stg}	-55~+175	$^\circ\text{C}$

Thermal Characteristics

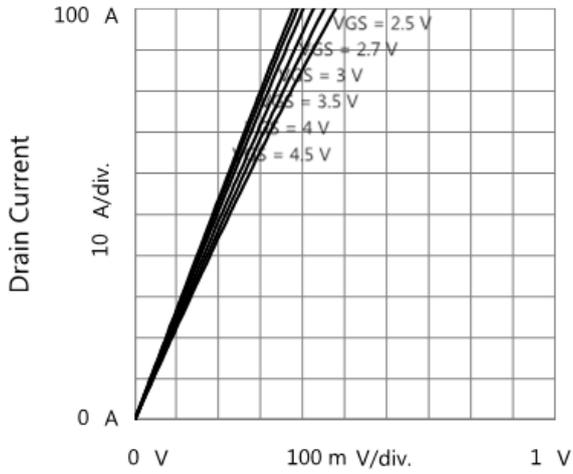
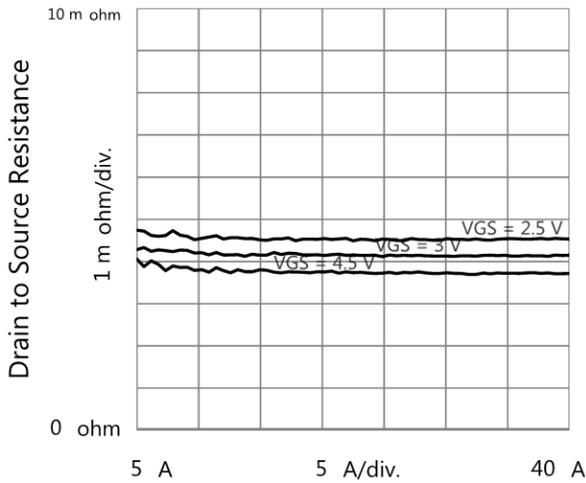
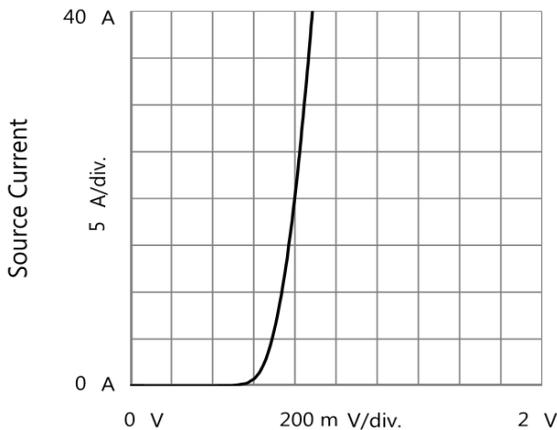
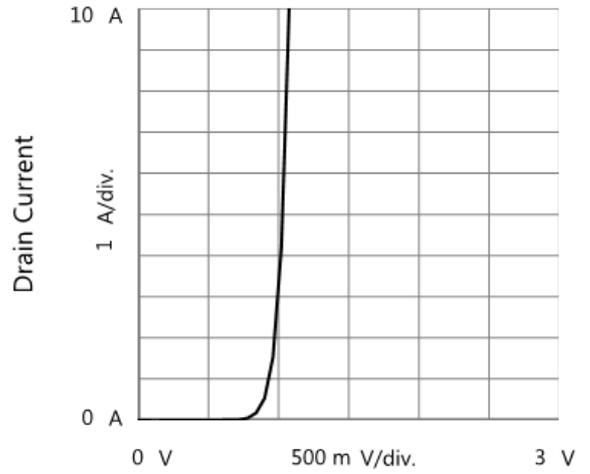
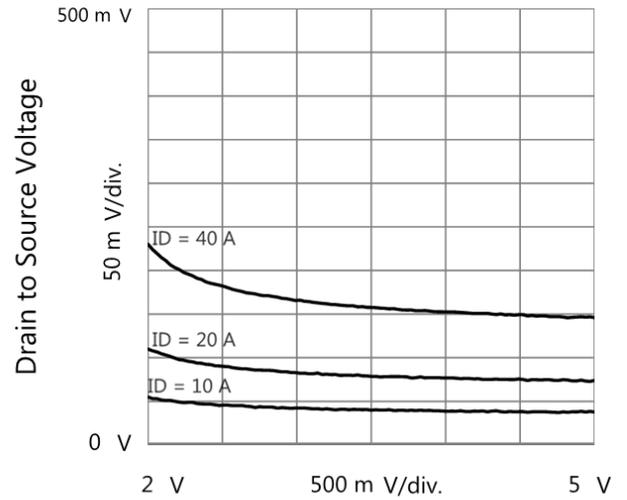
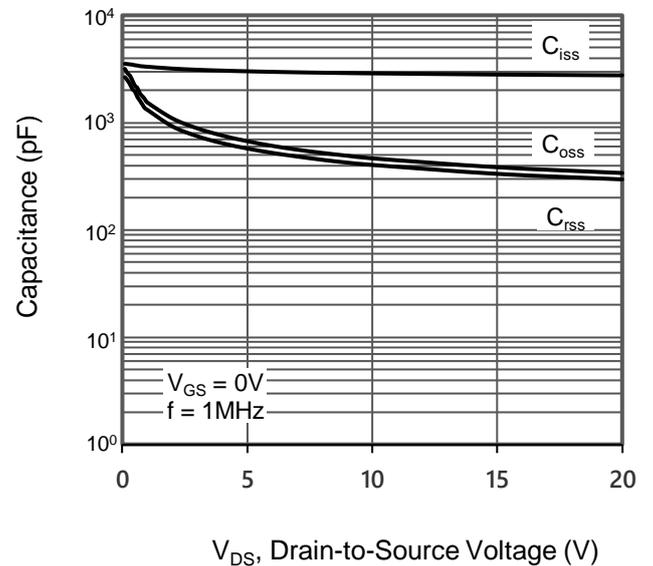
Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-Case (note1)	$R_{\theta JC}$	2.3	$^\circ\text{C}/\text{W}$
Thermal Resistance Junction-Ambient 1 ($t \leq 10\text{s}$) (note1)	$R_{\theta JA}$	62	$^\circ\text{C}/\text{W}$

Electrical Characteristics $T_J = 25^\circ\text{C}$ unless otherwise specified						
Parameter	Symbol	Test Conditions	Value			Unit
			Min.	Typ.	Max.	
Static						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = 250\mu A$	20	--	--	V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 20V, V_{GS} = 0V, T_J = 25^\circ\text{C}$	--	--	1	μA
		$V_{DS} = 20V, V_{GS} = 0V, T_J = 100^\circ\text{C}$	--	--	5	μA
Gate-Source Leakage	I_{GSS}	$V_{GS} = \pm 12V$	--	--	± 100	nA
Gate-Source Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\mu A$	0.5	0.75	1	V
Drain-Source On-Resistance (note2)	$R_{DS(on)}$	$V_{GS} = 4.5V, I_D = 30A$	--	3.1	4.8	$m\Omega$
		$V_{GS} = 2.5V, I_D = 24A$	--	3.8	7.5	$m\Omega$
Dynamic						
Input Capacitance	C_{iss}	$V_{GS} = 0V, V_{DS} = 15V, f = 1.0MHz$	--	2823	--	pF
Output Capacitance	C_{oss}		--	383	--	
Reverse Transfer Capacitance	C_{rss}		--	335	--	
Total Gate Charge (4.5V)	Q_g	$V_{DD} = 10V, I_D = 40A, V_{GS} = 4.5V$	--	39	--	nC
Gate-Source Charge	Q_{gs}		--	5.2	--	
Gate-Drain Charge	Q_{gd}		--	14	--	
Turn-on Delay Time	$t_{d(on)}$	$V_{DS} = 10V, V_{GS} = 4.5V, R_G = 3.5\Omega$	--	32	--	ns
Turn-on Rise Time	t_r		--	4	--	
Turn-off Delay Time	$t_{d(off)}$		--	124	--	
Turn-off Fall Time	t_f		--	41	--	
Body Diode Characteristics						
Continuous Body Diode Current	I_S	$T_C = 25^\circ\text{C}$	--	--	80	A
Pulsed Diode Forward Current	I_{SM}		--	--	320	
Body Diode Voltage	V_{SD}	$T_J = 25^\circ\text{C}, I_{SD} = 40A, V_{GS} = 0V$	0.4	--	1	V

Notes

1. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
2. The data tested by pulsed , pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$
3. The EAS data shows Max. rating . The test condition is $V_{DD} = 20V, V_{GS} = 10V, L = 0.5mH$
4. The power dissipation is limited by 175 $^\circ\text{C}$ junction temperature
5. The data is theoretically the same as ID and IDM , in real applications , should be limited by total power dissipation.

Typical Characteristics $T_J = 25^\circ\text{C}$, unless otherwise noted

Output Characteristics

Drain to Source Resistance vs. Drain Current

Drain Current
Body Diode Forward Characteristics

Source to Drain Voltage
Transfer Characteristics

Gate to Source Voltage
Drain to Source Voltage vs. Gate to Source Voltage

Gate to Source Voltage


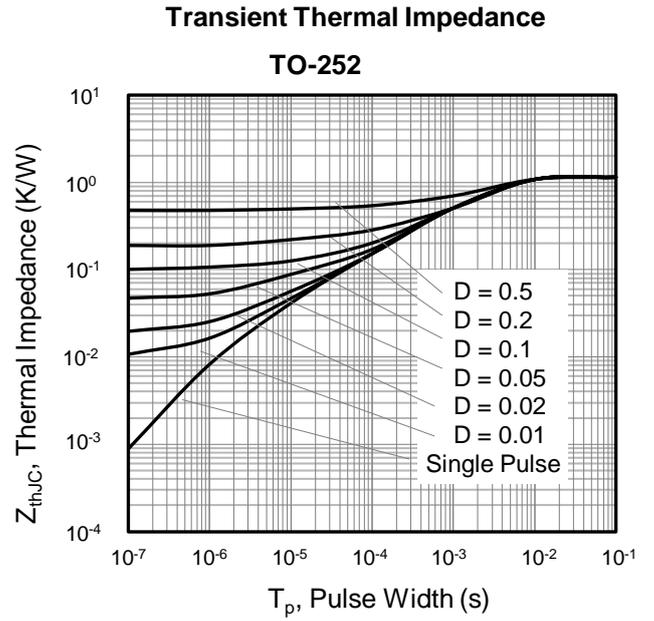
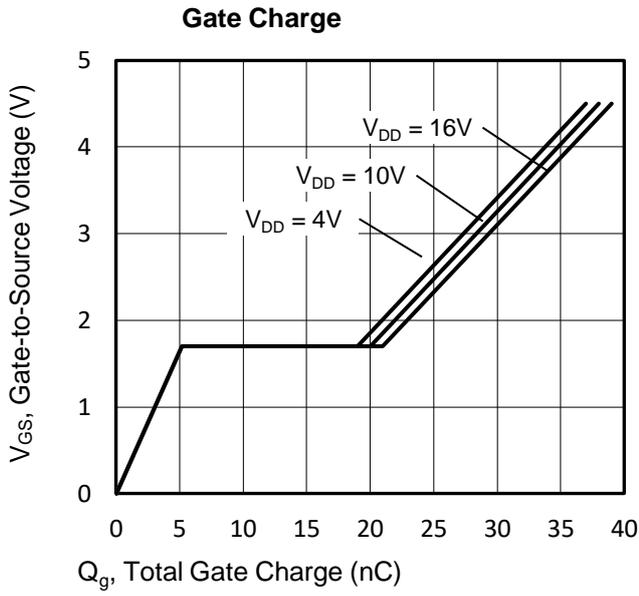
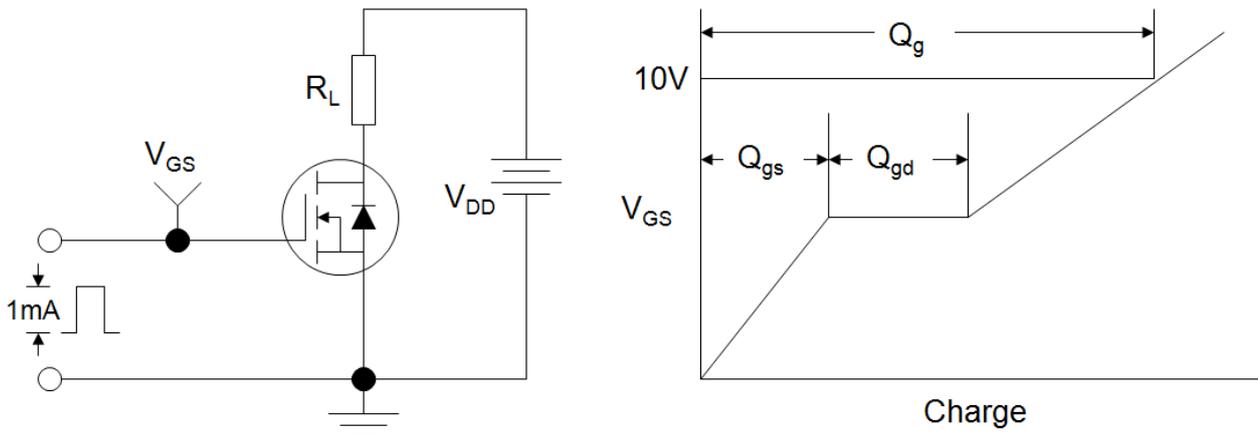
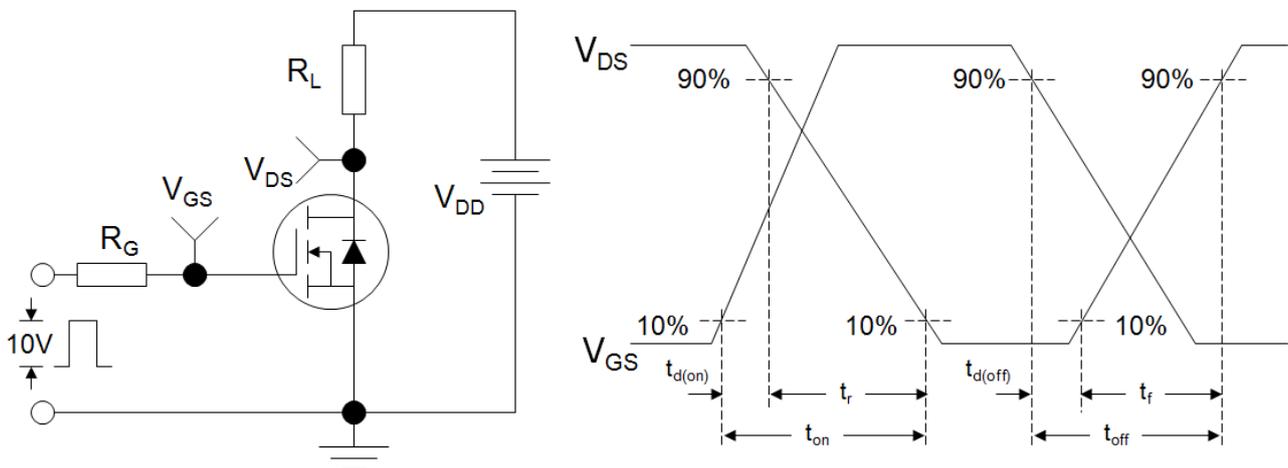
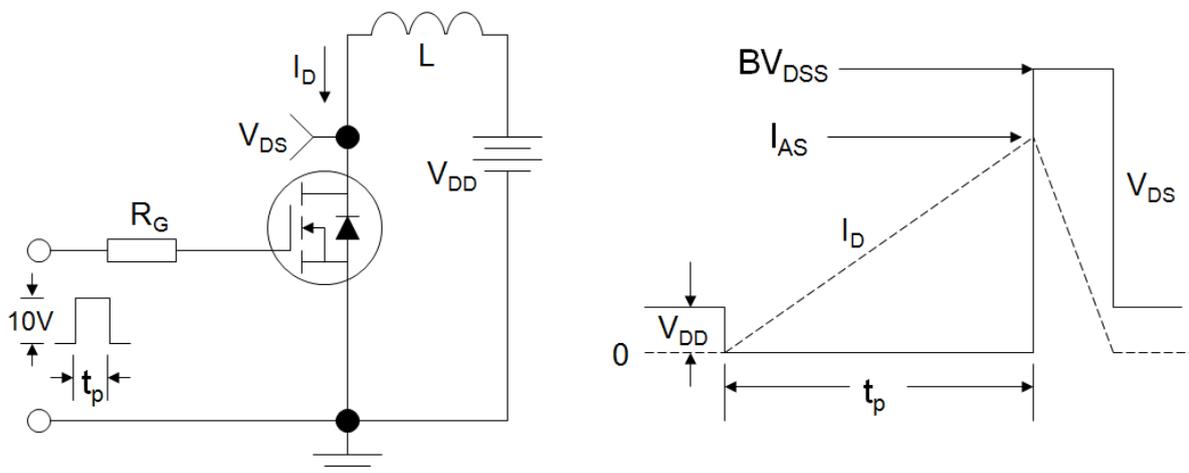
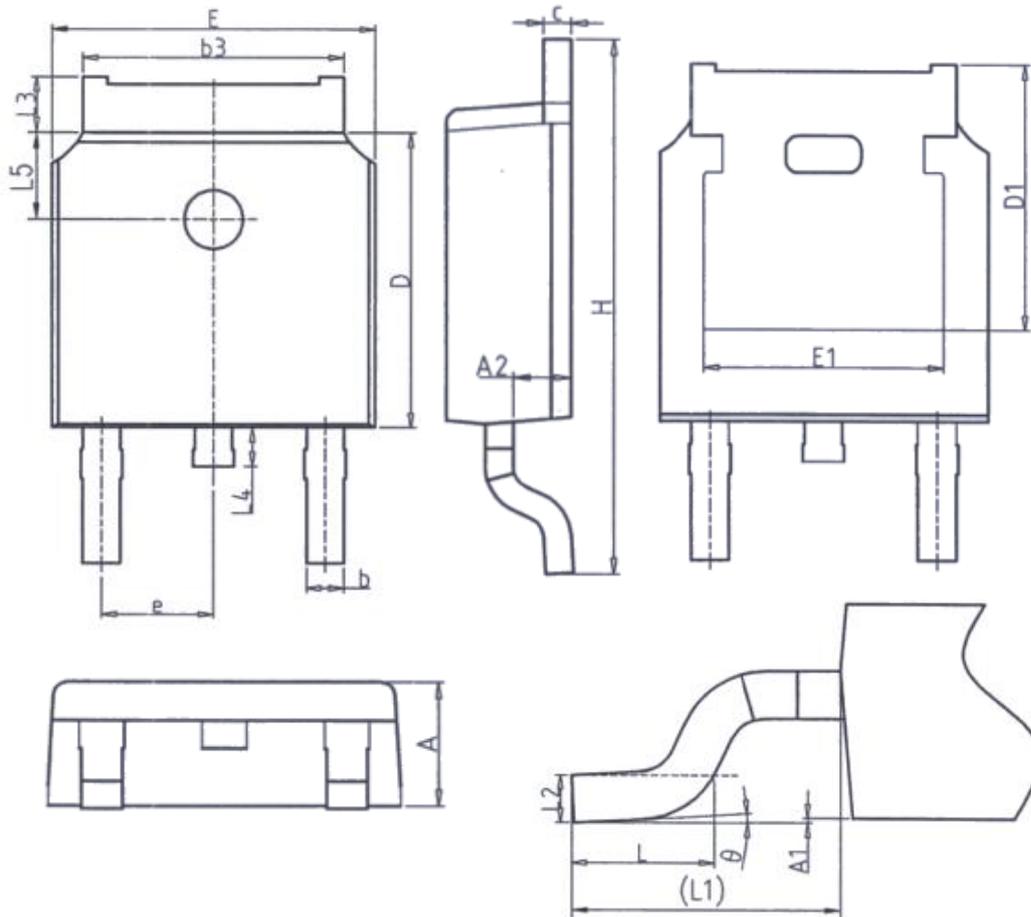
Typical Characteristics $T_J = 25^\circ\text{C}$, unless otherwise noted


Figure A: Gate Charge Test Circuit and Waveform

Figure B: Resistive Switching Test Circuit and Waveform

Figure C: Unclamped Inductive Switching Test Circuit and Waveform


TO-252


Unit: mm		
Symbol	Min.	Max.
A	2.20	2.40
A1	0.00	0.20
A2	0.97	1.17
b	0.68	0.90
b3	5.20	5.50
c	0.43	0.63
D	5.98	6.22
D1	5.30REF	
E	6.40	6.80
E1	4.63	-

Unit: mm		
Symbol	Min.	Max.
e	2.286BSC	
H	9.40	10.50
L	1.38	1.75
L1	2.90REF	
L2	0.51BSC	
L3	0.88	1.28
L4	-	1.00
L5	1.65	1.95
θ	0°	8°

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